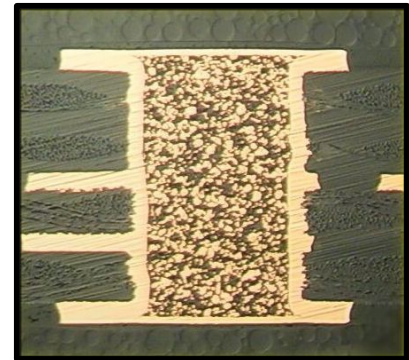


## Tatsuta AE3030 Features vs. CB100

- Much smaller Copper particle size => better paste penetration of small vias
- 100% solids material => shorter bake cycles, due to no solvent content
- Very high Tg
- Very high thermal conductivity => double that of CB100
- Much more cost effective than CB100 => 100g of AE3030 is 30% more material than CB100 based on volume
- Listed on <http://outgassing.nasa.gov>



	<b>Tatsuta AE3030</b>	<b>DuPont CB100</b>
Filling	Silver coated Copper Powder	Silver coated Copper & Silver particles
Cu particle size	0.24 to 0.3 mil	Up to 5 mil
Resin	Epoxy	Epoxy
% solid content	100%	92%
Color	Grey	Silver
Viscosity	150 PaS	130 PaS
Density*	4.2 g / cm <sup>3</sup>	5.5 g / cm <sup>3</sup>
Shelf Life	1.5 months	3 months
Pot Life at room temp.	24 hours	24 hours
Storage	Freezer	Freezer
Dry & Curing	60 min @ 170F	60 min & more @ 250F
	60 min @ 340F	60 min & more @ 350F
Volume resistivity	0.0003 Ohm cm	0.00016 Ohm cm
CTE	40	34
ppm/C	86	47 (claimed)
Thermal Conductivity	7.8 W/mK	3.5 W/mK
Tg	171	115
NASA Outgassing	Listed as approved material on <a href="http://outgassing.nasa.gov/">http://outgassing.nasa.gov/</a>	Not listed on this website